1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection in a DSN0603-2 (SOD962-2) leadless ultra small Chip-Scale Package (CSP).

2. Features and benefits

- Average forward current I_{F(AV)} ≤ 0.5 A
- Reverse voltage V_R ≤ 40 V
- Low forward voltage typ. V_F = 250 mV
- Low reverse current typ. I_R = 3 μA
- Package height typ. 0.3 mm

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Ultra high speed switching
- LED backlight for mobile application

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|--------------------|-------------------------|---|-----|-----|------|-----|------|
| I _{F(AV)} | average forward current | δ = 0.5; f = 20 kHz; $T_{amb} \le 100$ °C; square wave | [1] | - | - | 0.5 | А |
| | | δ = 0.5; f = 20 kHz; $T_{sp} \le$ 140 °C; square wave | | - | - | 0.5 | А |
| V_R | reverse voltage | T _j = 25 °C | | - | - | 40 | V |
| V _F | forward voltage | I_F = 10 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | | - | 250 | 320 | mV |
| I _R | reverse current | $V_R = 10 \text{ V}; T_j = 25 \text{ °C}; \text{ pulsed}$ | | - | 3 | 20 | μA |
| t _{rr} | reverse recovery time | I_F = 500 mA; I_R = 500 mA; $I_{R(meas)}$ = 100 mA; T_j = 25 °C | | - | 1.25 | - | ns |

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.



5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|----------------------|----------------|
| 1 | K | cathode[1] | | 1 - 2 |
| 2 | Α | anode | | sym001 |
| | | | Transparent top view | |
| | | | DSN0603-2 (SOD962-2) | |

^[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | |
|--------------|-----------|--|----------|--|--|
| | Name | Description | Version | | |
| PMEG4005AESF | DSN0603-2 | Leadless ultra small package; 2 terminals; body 0.6 x 0.3 x 0.3 mm | SOD962-2 | | |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|--------------|--------------|
| PMEG4005AESF | Z |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|--------------------|-------------------------------------|--|------------|-----|------|------|
| V _R | reverse voltage | T _j = 25 °C | | - | 40 | V |
| I _F | forward current | T _{sp} ≤ 138 °C; δ = 1 | | - | 0.71 | Α |
| I _{F(AV)} | average forward current | $\bar{\delta}$ = 0.5; f = 20 kHz; $T_{amb} \leq$ 100 °C; square wave | [1] | - | 0.5 | А |
| | | $\bar{\delta}$ = 0.5; f = 20 kHz; $T_{sp} \le$ 140 °C; square wave | | - | 0.5 | А |
| I _{FRM} | repetitive peak forward current | t_p = 1 ms; δ ≤ 0.25 | | - | 1.2 | Α |
| I _{FSM} | non-repetitive peak forward current | t_p = 8 ms; $T_{j(init)}$ = 25 °C; square wave | | - | 3.5 | А |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | <u>[2]</u> | - | 405 | mW |
| | | | [3] | - | 660 | mW |
| | | | [1] | - | 1200 | mW |
| Tj | junction temperature | | | - | 150 | °C |
| T _{amb} | ambient temperature | | | -55 | 150 | °C |
| T _{stg} | storage temperature | | | -65 | 150 | °C |

- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm² each.

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|--|--|------------|--------|-----|-----|-----|------|
| R _{th(j-a)} thermal resistance from junction to ambient | | | [1][2] | - | - | 310 | K/W |
| | | | [1][3] | - | - | 190 | K/W |
| | ambient | | [1][4] | - | - | 105 | K/W |
| R _{th(j-sp)} | thermal resistance from junction to solder point | | [5] | - | - | 40 | K/W |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm² each.
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [5] Soldering point of anode tab.

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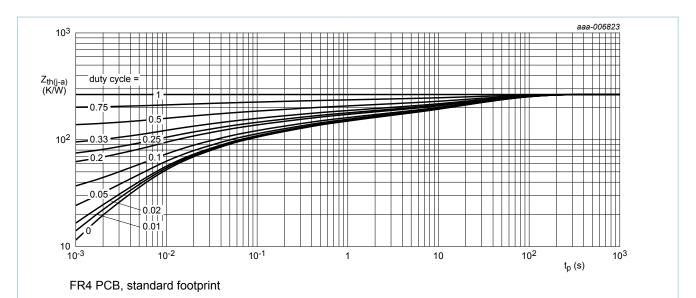
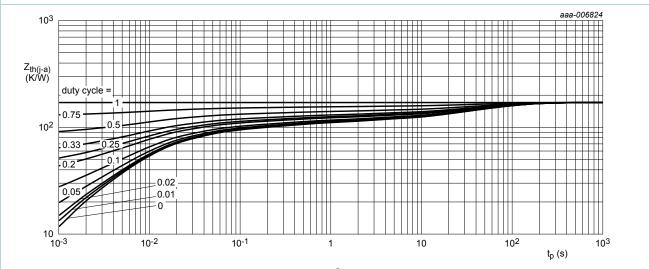
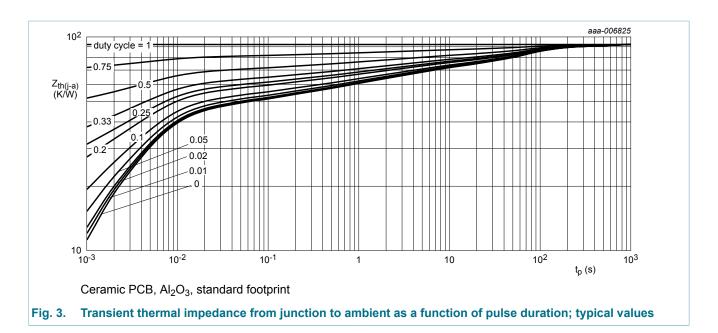


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for anode and cathode 1 cm² each

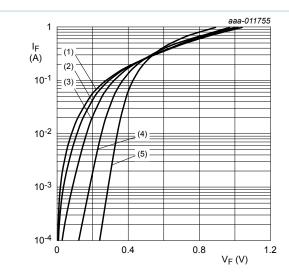
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------|---------------------------|---|-----|------|-----|------|
| $V_{(BR)R}$ | reverse breakdown voltage | I_R = 100 μA; t_p = 300 μs; $δ$ = 0.02; T_j = 25 °C | 40 | - | - | V |
| V _F | forward voltage | I_F = 0.1 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 120 | 185 | mV |
| | | I_F = 1 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 180 | 245 | mV |
| | | I_F = 10 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 250 | 320 | mV |
| | | I_F = 100 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 370 | 440 | mV |
| | | I_F = 200 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 450 | 525 | mV |
| | | I_F = 300 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 530 | 630 | mV |
| | | I_F = 400 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 600 | 730 | mV |
| | | I_F = 500 mA; t_p ≤ 300 μs; δ ≤ 0.02; T_j = 25 °C | - | 675 | 820 | mV |
| I _R | reverse current | V _R = 10 V; T _j = 25 °C; pulsed | - | 3 | 20 | μA |
| | | V _R = 40 V; T _j = 25 °C; pulsed | - | 13 | 80 | μA |
| C _d | diode capacitance | V _R = 1 V; f = 1 MHz; T _j = 25 °C | - | 18 | - | pF |
| | | V _R = 10 V; f = 1 MHz; T _j = 25 °C | - | 7 | - | pF |
| t _{rr} | reverse recovery time | I_F = 500 mA; I_R = 500 mA; $I_{R(meas)}$ = 100 mA; T_j = 25 °C | - | 1.25 | - | ns |



pulsed condition

(1) $T_i = 150 \, ^{\circ}C$

(2) $T_i = 125 \, ^{\circ}C$

(3) $T_j = 85 \, ^{\circ}C$

(4) $T_i = 25 \, ^{\circ}C$

(5) $T_i = -40 \, ^{\circ}\text{C}$

Fig. 4. Forward current as a function of forward voltage; typical values

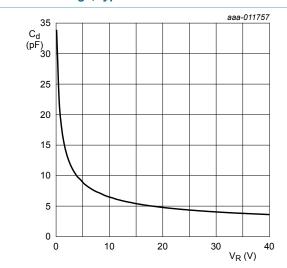
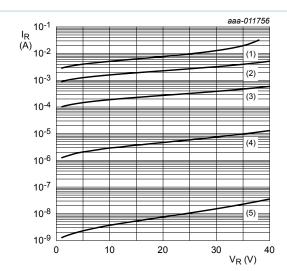


Fig. 6. Diode capacitance as a function of reverse voltage; typical values

 $f = 1 \text{ MHz}; T_{amb} = 25 \text{ °C}$



pulsed condition

(1) $T_i = 150 \,^{\circ}\text{C}$

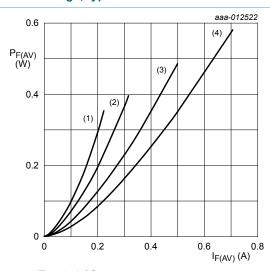
(2) $T_i = 125 \, ^{\circ}C$

(3) $T_j = 85 \, ^{\circ}C$

(4) $T_i = 25 \,^{\circ}C$

(5) $T_i = -40 \, ^{\circ}\text{C}$

Fig. 5. Reverse current as a function of reverse voltage; typical values



T_i = 150 °C

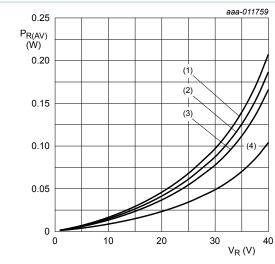
 $(1) \delta = 0.1$

 $(2) \delta = 0.2$

 $(3) \delta = 0.5$

 $(4) \delta = 1$

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



T_i = 125 °C

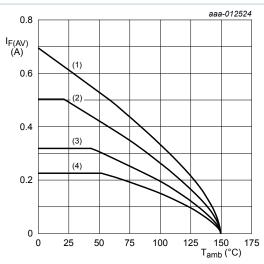
 $(1) \delta = 1$

 $(2) \delta = 0.9$

 $(3) \delta = 0.8$

 $(4) \delta = 0.5$

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

 $T_i = 150 \,{}^{\circ}\text{C}$

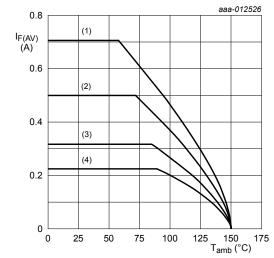
(1) δ = 1; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for anode and cathode 1

cm² each

 $T_i = 150 \,{}^{\circ}\text{C}$

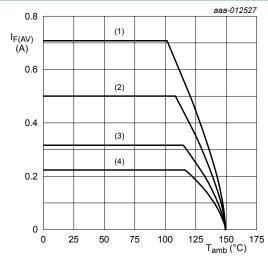
(1) δ = 1; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint

 $T_i = 150 \, ^{\circ}C$

(1) δ = 1; DC

(2) δ = 0.5; f = 20 kHz

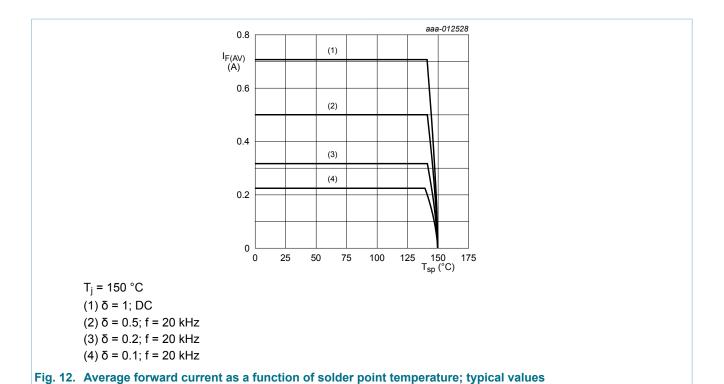
(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

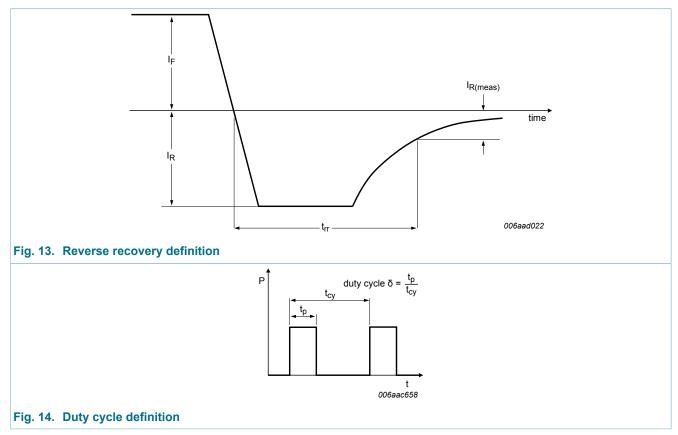
Fig. 11. Average forward current as a function of ambient temperature; typical values

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11. Test information

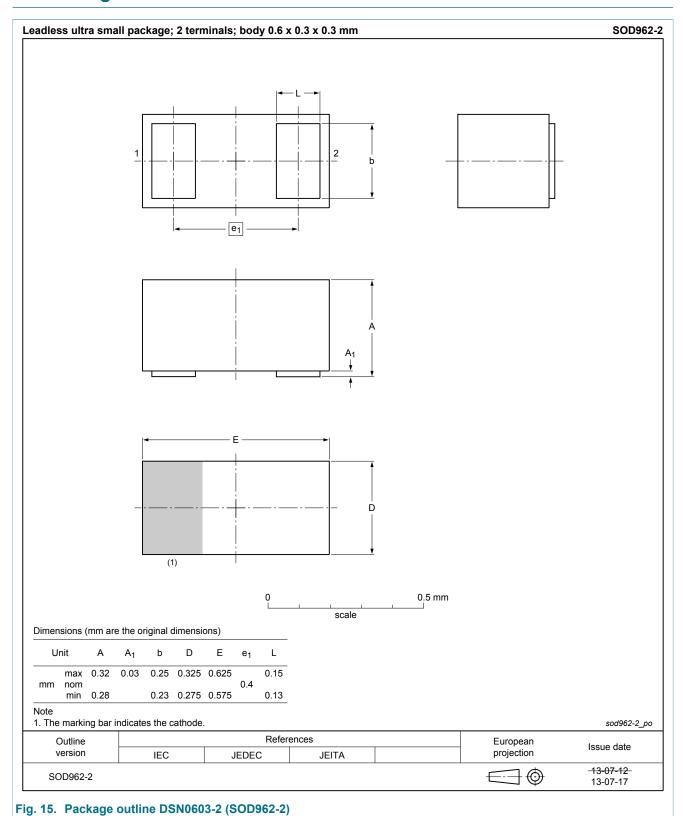


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The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

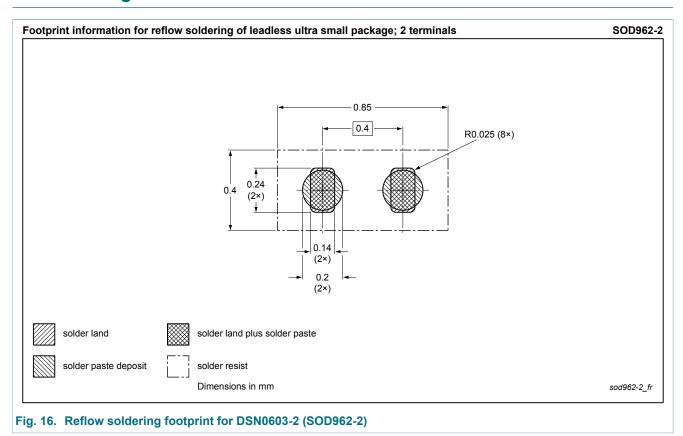
12. Package outline



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13. Soldering



14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|------------------|---------------------|------------------------|---------------|------------------|
| PMEG4005AESF v.2 | 20150206 | Product data sheet | - | PMEG4005AESF v.1 |
| Modifications: | Product status char | nged | | |
| PMEG4005AESF v.1 | 20140507 | Preliminary data sheet | - | - |

15. Legal information

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|--------------------------------------|--------------------|---|
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